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(54) **Title:** MICROELECTRONIC WORKPIECES AND METHODS FOR MANUFACTURING MICROELECTRONIC DEVICES USING SUCH WORKPIECES

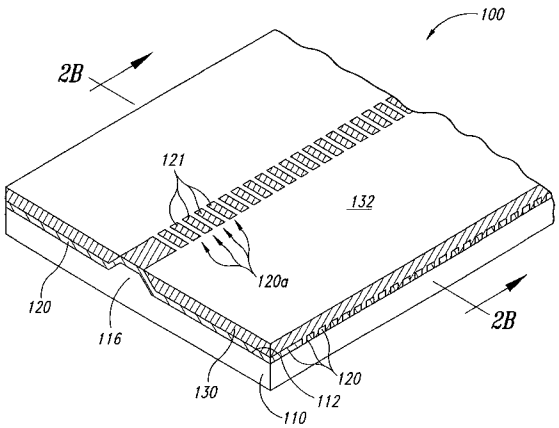


Fig. 2A

(57) **Abstract:** Microelectronic workpieces and methods for manufacturing microelectronic devices using such workpieces are disclosed. In one embodiment, a microelectronic assembly comprises a support member having a first side and a projection extending away from the first side. The assembly also includes a plurality of conductive traces at the first side of the support member. Some of the conductive traces include bond sites carried by the projection and having an outer surface at a first distance from the first side of the support member. The assembly further includes a protective coating deposited over the first side of the support member and at least a portion of the conductive traces. The protective coating has a major outer surface at a second distance from the first side of the support member. The second distance is approximately the same as the first distance such that the outer surface of the protective coating is generally co-planar with the outer surface of the bond sites carried by the projection. In several embodiments, a microelectronic die can be coupled to the corresponding bond sites carried by the projection in a flip-chip configuration.

WO 2008/112463 A1